Scoping study for future programme to "Demonstrate a methodology for reliable, packaged of Micro and Nanosystems"

Objective

Seed-corn funding for the development of a new proposal for funding to demonstrate a DfMM methodology on a key product Proposal submitted to UK DTI Technology Programme

Partners involved

QinetiQ, University of Lancaster
- If successful hoped European Partners (Tyndall, Politecnico Di Milano, IMEC, Fraunhofer IZM-Berlin) from original project to develop a "Methodology for the assessment of the impact of packaging on the performance and reliability of MEMS devices", would be able to participate in linked activities, initially with PATENT funding, but subsequently with their own National funding

Summary of results

Proposal entitled "Methodology for the assessment of the impact of packaging on micro/nanosystems submitted to the UK DTI Technology Programme, Technology Priority Area - Design, Modelling and Simulation.
The DTI assessors did not recommend the project progressed to the next phase for the following reasons

- There is insufficient explanation of the route to market
- The market potential of the project is poorly defined

However as the proposal was generic in nature it was difficult to identify specific industry pull for the activity in the UK

Offer to industry

Consultancy on packaging of MEMS

Contact

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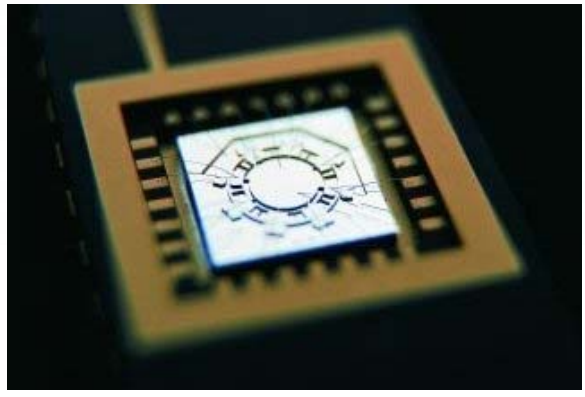
Project status

Finished



Picture courtesy of QinetiQ

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